

LINEAR SYSTEMS

Over Three Decades of Quality Through Innovation

LSK489

LOW NOISE LOW CAPACITANCE MONOLITHIC DUAL N-CANNEL JFET AMPLIFIER

FEATURES

ULTRA LOW NOISE	$e_n = 1.8nV/\sqrt{Hz}$
LOW INPUT CAPACITANCE	$C_{iss} = 4pF$

Features

- Reduced Noise due to process improvement
- Monolithic Design
- High slew rate
- Low offset/drift voltage
- Low gate leakage I_{gss} & I_g
- High CMRR 102 dB

Benefits

- Tight differential voltage match vs. current
- Improved op amp speed settling time accuracy
- Minimum Input Error trimming error voltage
- Lower intermodulation distortion

Applications

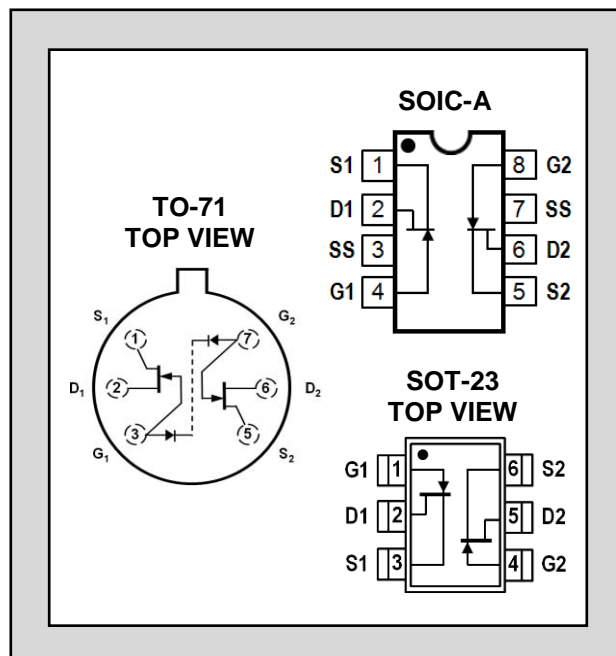
- Wide band differential Amps
- High speed temperature compensated single ended input amplifier amps
- High speed comparators
- Impedance Converters

Description

The LSK 489 series of high performance monolithic dual JFETs features extremely low noise, tight offset voltage and low drift over temperature specifications, and is targeted for use in a wide range of precision instrumentation applications. This series has a wide selection of offset and drift specifications. The SST series SO-8 package provided ease of manufacturing and the symmetrical pinout prevents improper orientation. The SO-8 package is available with tape and reel options for compatibility with automatic assembly methods. (See packaging data)

ABSOLUTE MAXIMUM RATINGS¹ @ 25 °C (unless otherwise stated)

Maximum Temperatures	
Storage Temperature	-55 to +150°C
Junction Operating Temperature	-55 to +150°C
Maximum Power Dissipation, TA = 25°C	
Continuous Power Dissipation, per side ⁴	300mW
Power Dissipation, total ⁵	500mW
Maximum Currents	
Gate Forward Current	$I_{G(F)} = 10mA$
Maximum Voltages	
Gate to Source	$V_{GSO} = 60V$
Gate to Drain	$V_{GDO} = 60V$



* For equivalent single version, see LSK189

MATCHING CHARACTERISTICS @ 25°C (unless otherwise stated)

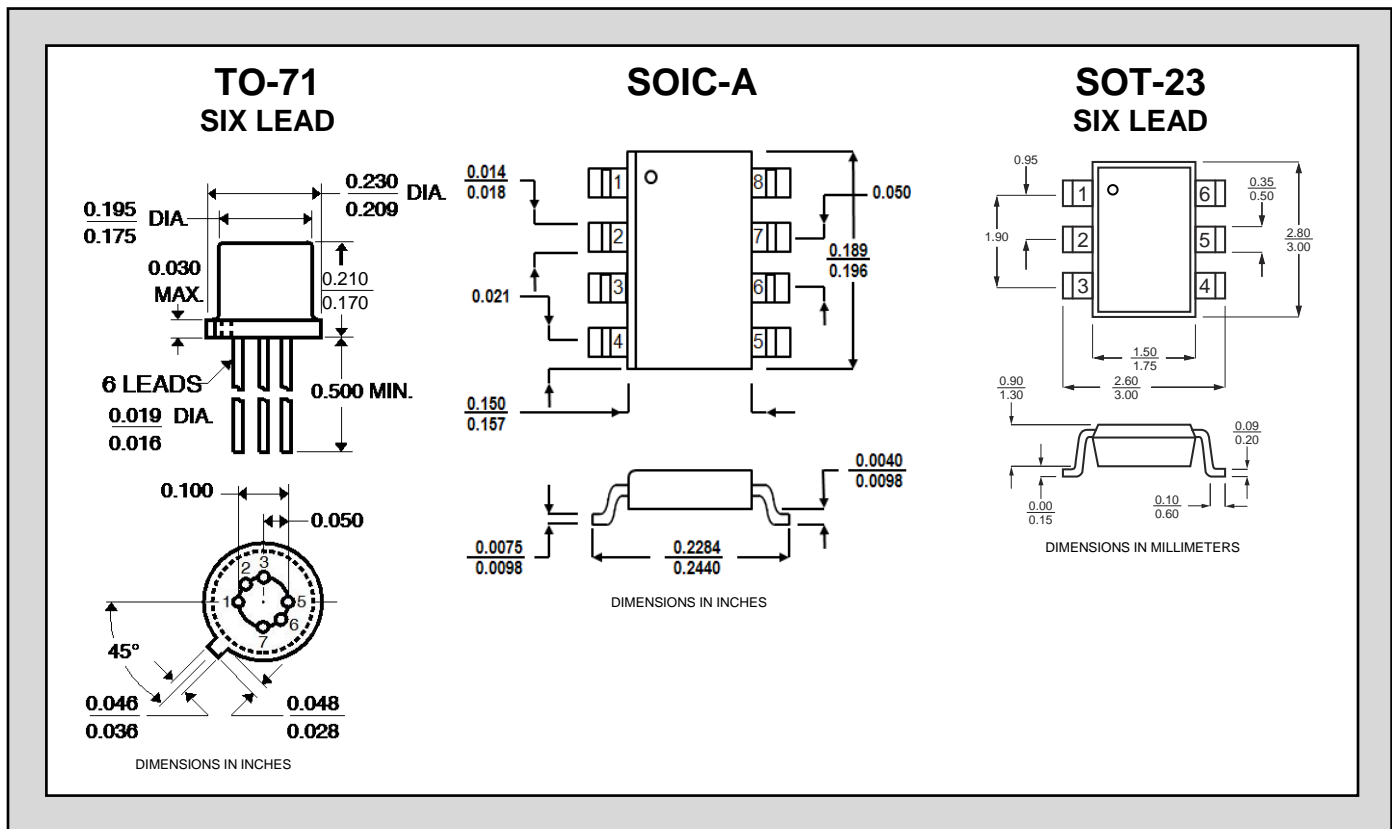
SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
$ V_{GS1} - V_{GS2} $	Differential Gate to Source Cutoff Voltage			20	mV	$V_{DS} = 10V, I_D = 1mA$
$\frac{I_{DSS1}}{I_{DSS2}}$	Gate to Source Saturation Current Ratio	0.9		1.0		$V_{DS} = 10V, V_{GS} = 0V$
CMRR	COMMON MODE REJECTION RATIO $-20 \log \Delta V_{GS1-2}/\Delta V_{DS} $	95	102		dB	$V_{DS} = 10V \text{ to } 20V, I_D = 200\mu A$

SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
e_n	Noise Voltage		2.0		nV/ \sqrt{Hz}	$V_{DS} = 15V, I_D = 2.0mA, f = 1kHz, NBW = 1Hz$
e_n	Noise Voltage		3.5		nV/ \sqrt{Hz}	$V_{DS} = 15V, I_D = 2.0mA, f = 10Hz, NBW = 1Hz$
C_{ISS}	Common Source Input Capacitance		4	8	pF	$V_{DS} = 15V, I_D = 500\mu A, f = 1MHz$
C_{RSS}	Common Source Reverse Transfer Capacitance			3	pF	

ELECTRICAL CHARACTERISTICS @ 25°C (unless otherwise stated)

SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
BV_{GSS}	Gate to Source Breakdown Voltage	-60			V	$V_{DS} = 0, I_D = -1nA$
$V_{(BR)G1-G2}$	Gate to Gate Breakdown Voltage	± 30	± 45		V	$I_G = \pm 1\mu A, I_D = I_S = 0A$ (Open Circuit)
$V_{GS(OFF)}$	Gate to Source Pinch-off Voltage	-1.5		-3.5	V	$V_{DS} = 15V, I_D = 1nA$
V_{GS}	Gate to Source Operating Voltage	-0.5		-3.5	V	$V_{DS} = 15V, I_D = 500\mu A$
I_{DSS}^2	Drain to Source Saturation Current	2.5	5	15	mA	$V_{DG} = 15V, V_{GS} = 0$
I_G	Gate Operating Current		-2	-25	pA	$V_{DG} = 15V, I_D = 200\mu A$ $T_A = 125^\circ C$
			-0.8	-10	nA	
I_{GSS}	Gate to Source Leakage Current			-100	pA	$V_{DG} = -15V, V_{DS} = 0$
G_{fs}	Full Conductance Transconductance	1500			μS	$V_{DG} = 15V, V_{GS} = 0, f = 1kHz$
G_{fs}	Transconductance	1000	1500		μS	$V_{DG} = 15V, I_D = 500\mu A$
G_{OS}	Full Output Conductance			40	μS	$V_{DG} = 15V, V_{GS} = 0$
G_{OS}	Output Conductance		1.8	2.7	μS	$V_{DG} = 15V, I_D = 200\mu A$
NF	Noise Figure			0.5	dB	$V_{DS} = 15V, V_{GS} = 0, R_G = 10M\Omega, f = 100Hz, NBW = 6Hz$

PACKAGE DIMENSIONS

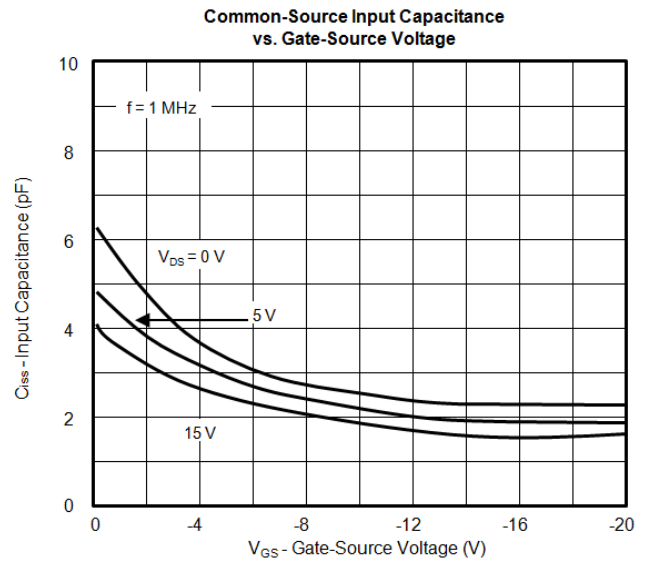
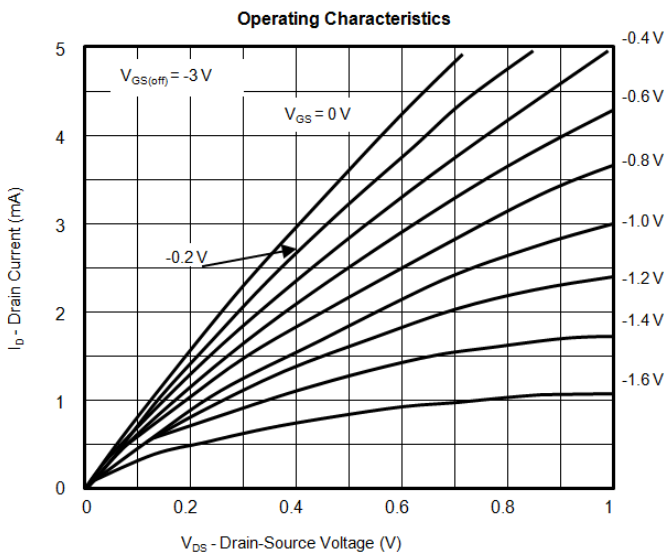
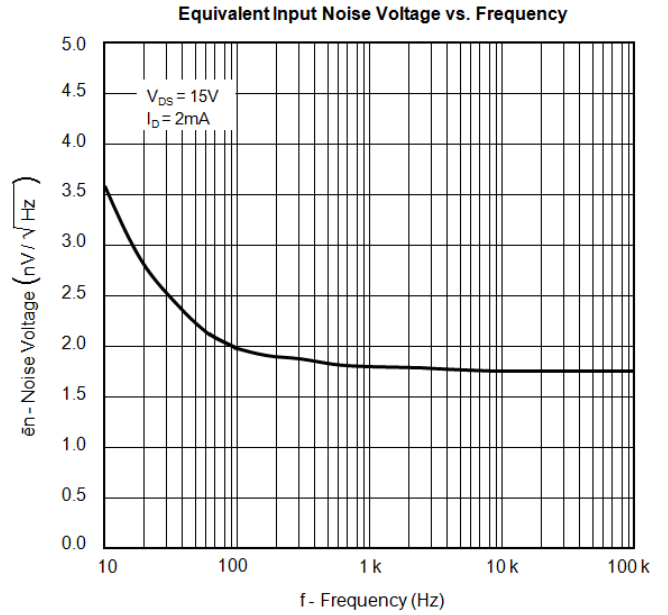
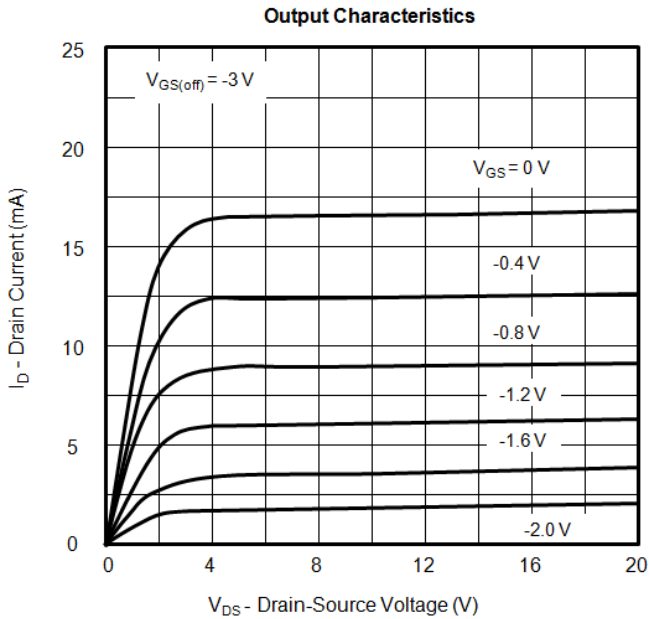
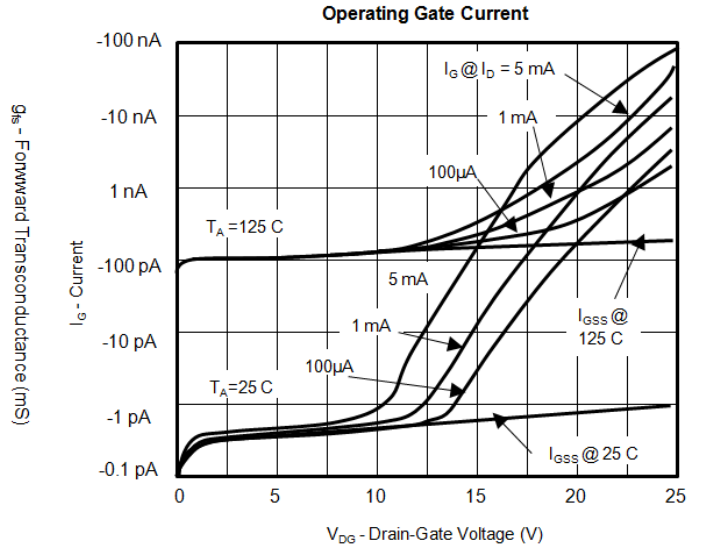
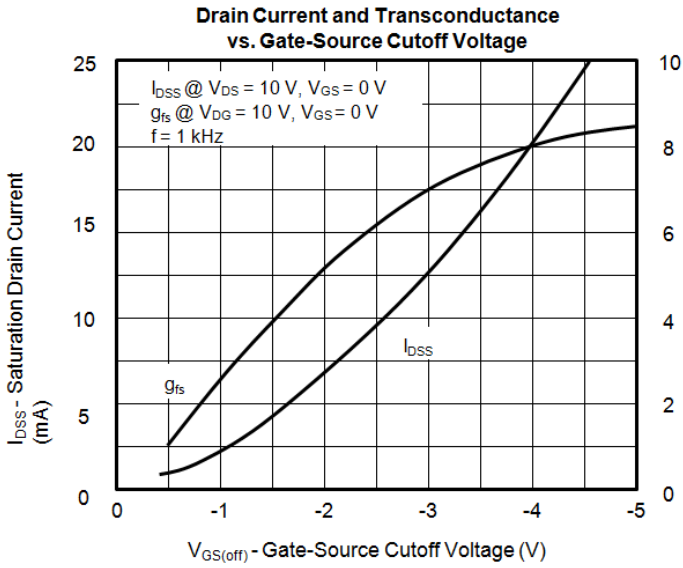


NOTES

1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. Pulse width $\leq 2_{ms}$.
3. All MIN/TYP/MAX Limits are absolute values. Negative signs indicate electrical polarity only.
4. Derate 2.4 mW/°C above 25°C.
5. Derate 4 mW/°C above 25°C.

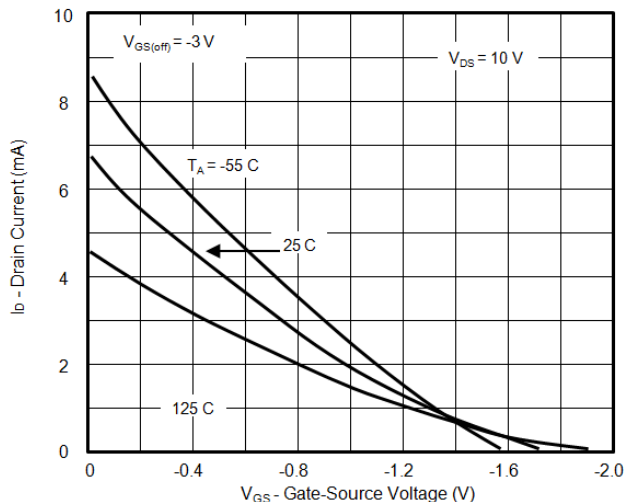
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Typical Characteristics

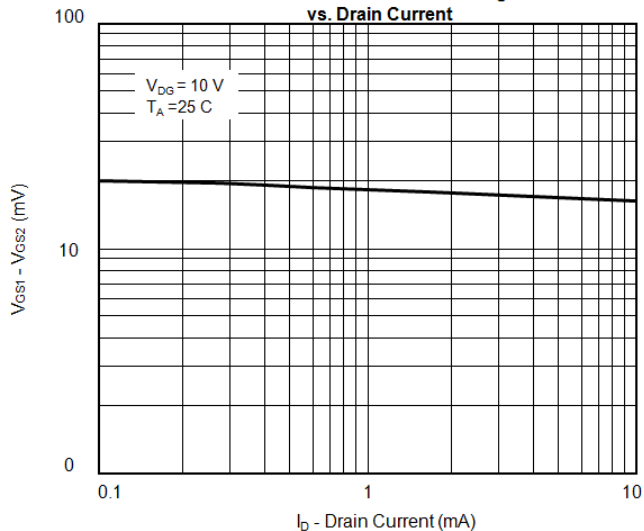


Typical Characteristics (Cont'd)

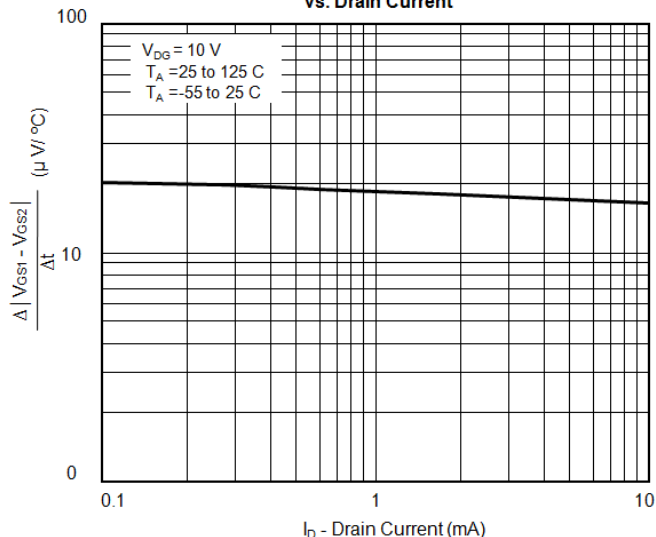
Transfer Characteristics



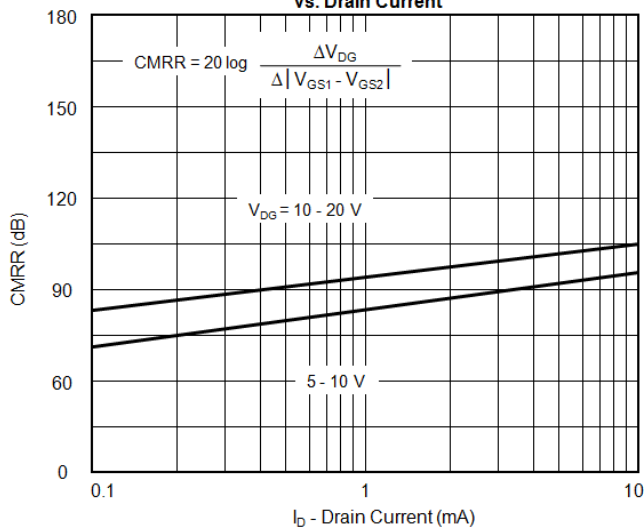
Gate-Source Differential Voltage vs. Drain Current



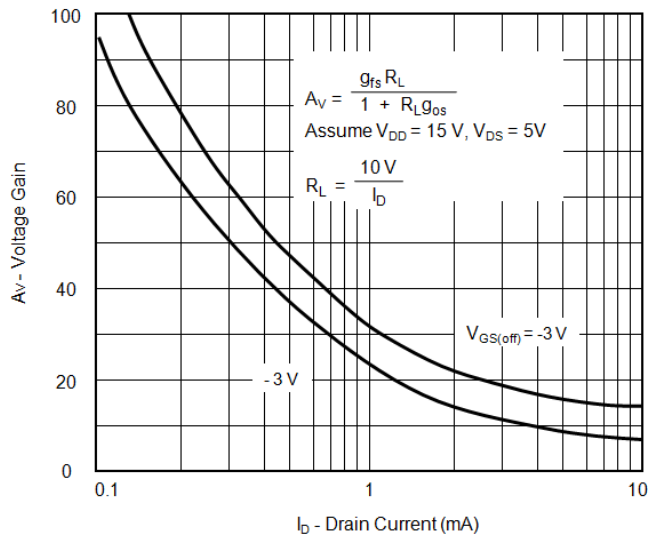
Voltage Differential with Temperature vs. Drain Current



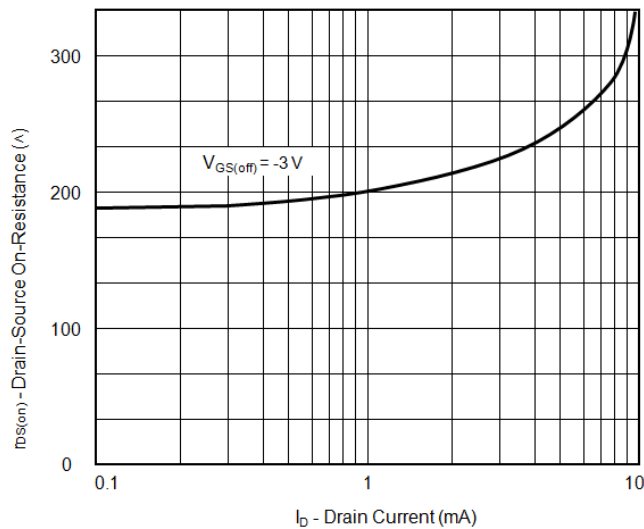
Common Mode Rejection Ratio vs. Drain Current



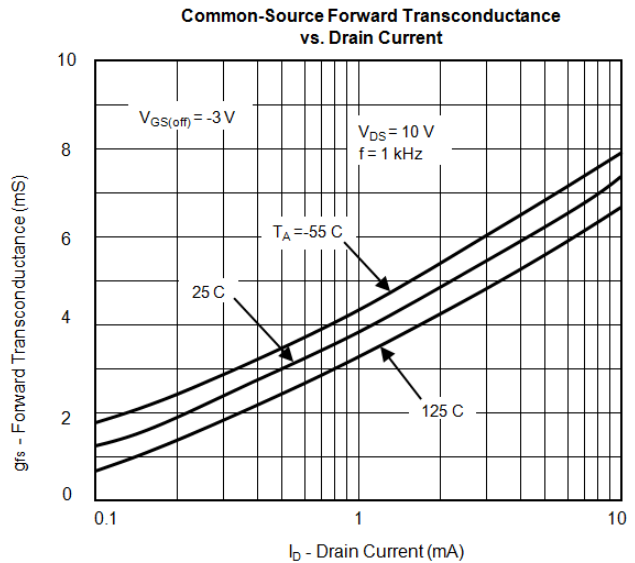
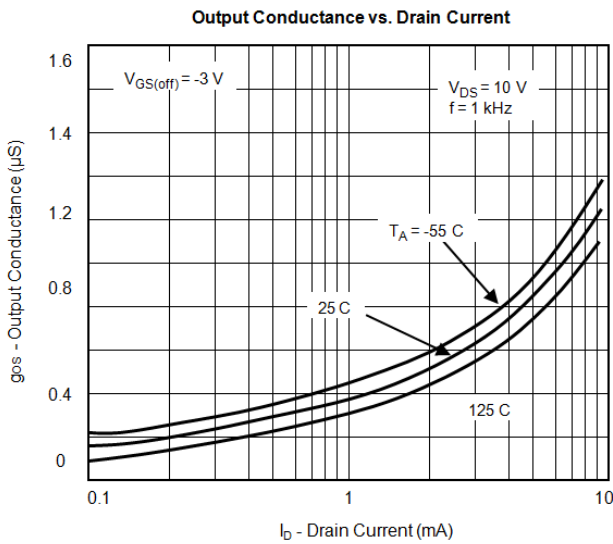
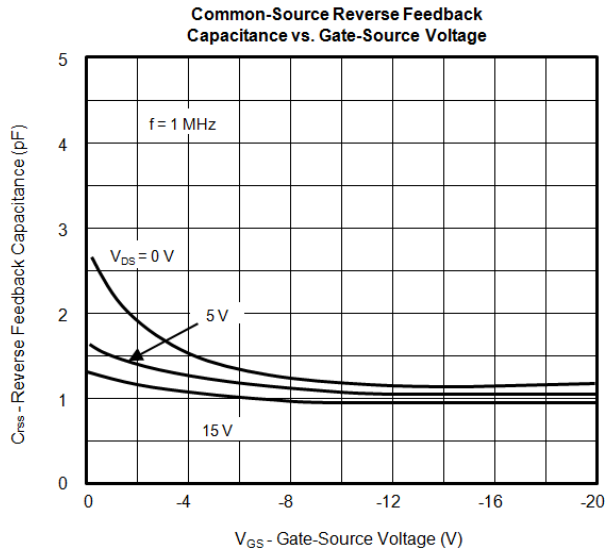
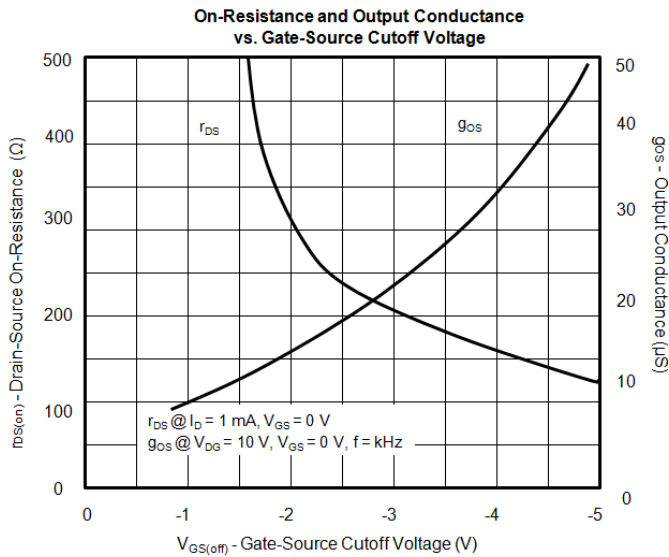
Circuit Voltage Gain vs. Drain Current



On-Resistance vs. Drain Current



Typical Characteristics (Cont'd)



Linear Integrated Systems (LIS), established in 1987, is third-generation precision semiconductor company providing high-quality discrete components. Expertise brought to LIS is based on processes and products developed at Amelco, Union Carbide, Intersil and Micro Power Systems by company Founder John H. Hall. Hall, a protégé of Silicon Valley legend Dr. Jean Hoerni, was the director of IC Development at Union Carbide, Co-Founder and Vice President of R&D at Intersil, and Founder/President of Micro Power Systems.